

CRYSTAL OSCILLATOR (Programmable)

OUTPUT: CMOS

SG-8101 series

• Frequency range: 0.67 MHz ~ 170 MHz (1 ppm Step)

• Supply voltage : 1.62 V ~ 3.63 V

 Function : Output enable (OE) or Standby (ST)

• Frequency tolerance, operating temperature:

±15 ppm (-40 °C ~ +85 °C) ±20 ppm, ±50 ppm (-40 °C ~ +105 °C)

: 2.5 x 2.0, 3.2 x 2.5, 5.0 x 3.2, 7.0 x 5.0 (mm) Package

• PLL technology to enable short lead time

• Available field oscillator programmer "SG-Writer II"



Specifications (characteristics)

Iter	m	Symbol			cations	Conditions/Remarks				
Supply voltage		V _{cc}	1.80 \		2.50 V Typ.	3.30 V Typ.			_	
117			1.62 V ~ 1.98 V		2.20 V ~ 2.80 V	2.70 V ~ 3.63 V				
	, ,	f _O			~ 170 MHz					
Storage temperature T_stg				+125 °C	Storage as single p	Storage as single product.				
Operating temperature T_use		T_use			~ +85 °C				-	
3 1 1 1 1					+105 °C			25.00	-	
Frequency tolerance*1					5 × 10 ⁻⁶		T_use = -40 °C ~ +			
		f_tol) × 10 ⁻⁶					
			2.2 m / May) × 10 ⁻⁶	2.5 m A. May	T_use = -40 °C ~	+105 °C	<i>;</i>	
			3.2 mA Max.	3.3 mA Max.	3.4 mA Max.	3.5 mA Max.	T_use = +105 °C	No load, f _O = 20 MHz		
Current consum	ption	Icc	5.5 mA Max.	nA Typ. 5.8 mA Max.	2.9 mA Typ. 6.7 mA Max.	3.0 mA Typ. 8.1 mA Max.	T_use = +25 °C T_use = +105 °C	ļ		
				nA Typ.	5.7 mA Typ.	6.8 mA Typ.	T_use = +105 °C T use = +25 °C	No load, f _O = 170 MHz		
Output disable	current	I dis	3.2 mA Max.	3.2 mA Max.	3.3 mA Max.	3.5 mA Max.	$OE = GND, f_O = 17$			
	Juliell	i_uis	0.9 µA Max.	1.0 µA Max.	1.5 µA Max.	2.5 µA Max.	$T_use = +105 ^{\circ}C$	O IVII IZ		
Standby curren	t	I_std	0.3 μA Typ.	0.4 μA Typ.	0.5 μA Typ.	1.1 µA Typ.	T use = +25 °C	ST = C	GND	
Symmetry		SYM	σ.σ μ. τ. γρ.	~ 55 %	50 % V _{CC} Level					
<u> </u>					I _{OH} /I _{OL} Conditions [mA]					
		V _{OH}			Rise/Fall time	V_{CC}	*A *B *C *D			
				90 % \	_{CC} Min.		Default (f _O > 40 MHz)			
0					Fast	2.5 3.5 4.0 5.0				
Output voltage (DC characteris	tice)				Default (f _O ≤ 40 MHz)	-1.5 -2.0 -2.5 -3.0 1.5 2.0 2.5 3.0				
(DC characteris	ucs)		10 % V _{CC} Max.					I _{OL}	-1.0 -1.5 -2.0 -2.5	
		V _{OL}					Slow	I _{OL} 1.0 1.5 2.0		
		· OL			*A: 1.62 V ~ 1.98 V, *B: 1.98 V ~ 2.20					
					*C: 2.20 V ~ 2.80 V, *D: 2.70 V ~ 3.63 \					
Output load cor	ndition	L_CMOS		oF Max.	-					
Input voltage		V _{IH}		70 % \		OE or ST				
mpat voltago		V_{IL}		30 % V	cc Max.		02 0. 0.			
	Default			3.0	ns Max.		f _O > 40 MHz			
Rise and Fall	Delault			6.0	ns Max.		f _O ≤ 40 MHz		20 % - 80 % V _{cc.}	
time	Fast	tr/tf		3.0	ns Max.		f _O = 0.67 MHz ~ 17	0 MHz	L_CMOS = 15 pF	
	Slow	7		10.0	ns Max.		f _O = 0.67 MHz ~ 20			
Disable Time t		t_stp		ıs Max.		Measured from the time OE or ST pin crosses 30 %				
Enable Time		t_sta		us Max.		V _{CC} Measured from the time OE pin crosses 70 % V _{CC}				
Resume Time		t_res			ns Max.		Measured from the time ST pin crosses 70 % V _{CC}			
Start-up time		t_str		3 n	ns Max.		Measured from the time V _{CC} reaches its rated minimum value, 1.62 V			
Frequency aging f_agir			This is included in frequency tolerance specification.				+25 °C, first year			

^{*1} Frequency tolerance includes initial frequency tolerance, temperature variation, supply voltage variation, reflow drift, load drift and aging (+25 °C, 1 year).

Pin description

	ii dooonpiioii									
Pin	Name	I/O type		Function						
	OE	Input	Output enable	High: Specified frequency output from OUT pin						
	OL .	Input	Output eriable	Low: Out pin is low (weak pull down), only output driver is disabled.						
1				High: Specified frequency output from OUT pin						
	ST	Input	Standby	Low: Out pin is low (weak pull down),						
				Device goes to standby mode. Supply current reduces to the least as I_std.						
2	GND	Power	Ground							
3	OUT	Output	Clock output							
4	Vcc	Power	Power supply							

Product Name

 $\underline{\mathsf{SG-8101CG}}\,\underline{\mathsf{170.000000MHz}}\,\,\underline{\mathsf{T}}\,\,\underline{\mathsf{C}}\,\,\underline{\mathsf{H}}\,\,\underline{\mathsf{P}}\,\,\underline{\mathsf{A}}$ 45678

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①Model, ②Package type, ③Frequency, ④Supply voltage,

⑤Frequency tolerance, ⑥Operating temperature,

⑦Function, ®Rise/Fall time

②Package type Supply voltage CA: 7.0 mm x 5.0 mm T: 1.8 V ~ 3.3 V Typ.

CB: 5.0 mm x 3.2 mm

CE: 3.2 mm x 2.5 mm

CG: 2.5 mm x 2.0 mm

⑤Frequency tolerance B: 15 x 10⁻⁶ C: 20 x 10-6 J: 50 x 10⁻⁶

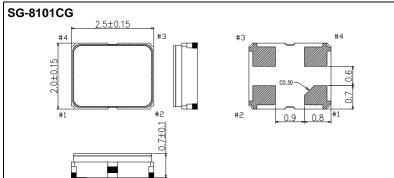
G: -40 °C ~ +85 °C H: -40 °C ~ +105 °C

® Rise/Fall time A: Default B: Fast C: Slow

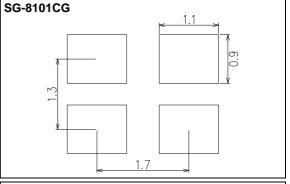
⑦Function
P: Output Enable
S: Standby

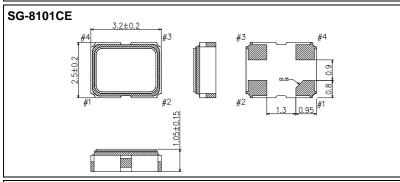
Available combination		CA: 7.0 mm x 5.0 mm			CB: 5.0 mm x 3.2 mm			CE: 3.2 mm x 2.5 mm			CG: 2.5 mm x 2.0 mm		
Frequency tolerance		B: 15 x 10 ⁻⁶	C: 20 x 10 ⁻⁶	J: 50 x 10 ⁻⁶	B: 15 x 10 ⁻⁶	C: 20 x 10 ⁻⁶	J: 50 x 10 ⁻⁶	B: 15 x 10 ⁻⁶	C: 20 x 10 ⁻⁶	J: 50 x 10 ⁻⁶	B: 15 x 10 ⁻⁶	C: 20 x 10 ⁻⁶	J: 50 x 10 ⁻⁶
Operating	G: -40 °C ~ +85 °C	✓			✓			~			✓		
temperature	H: -40 ℃ ~ +105 ℃		✓	✓		✓	✓		✓	✓		✓	✓

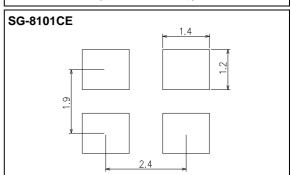
External dimensions (Unit: mm)

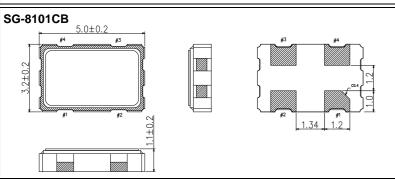


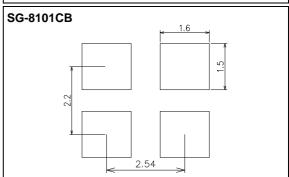
Footprint (Recommended) (Unit: mm)

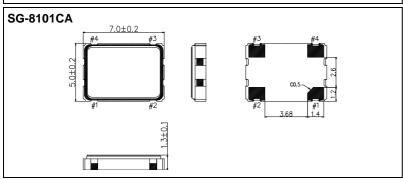


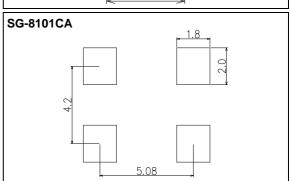












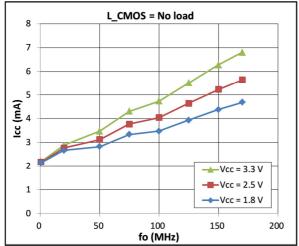
■Notes:

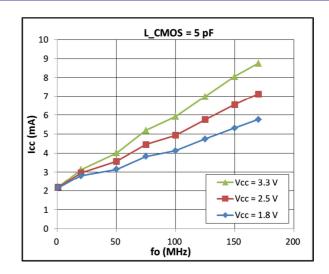
In order to achieve optimum jitter performance, the 0.1 μF capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

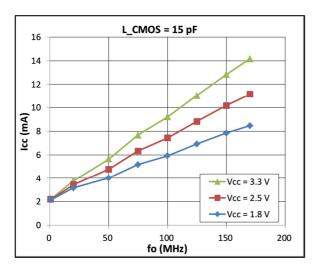


Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)

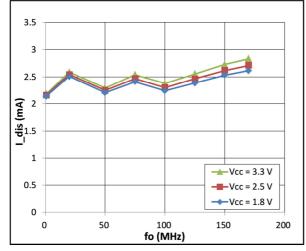
Current Consumption



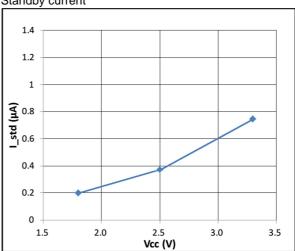




Output disable current



Standby current

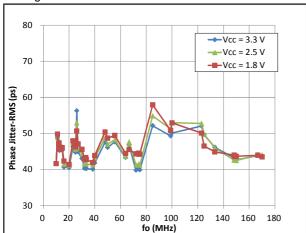


■Notes:

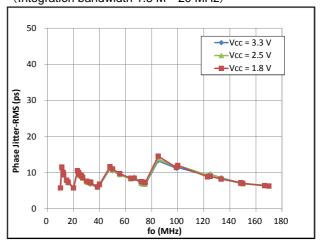
Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)

Phase Jitter RMS

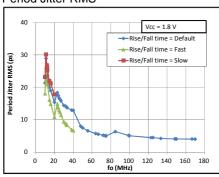
(Integration bandwidth 12 k-20 MHz)

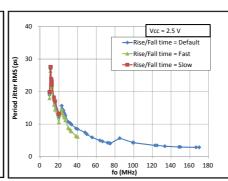


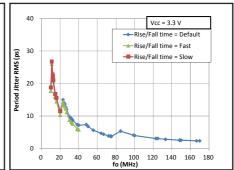
Phase Jitter RMS
(Integration bandwidth 1.8 M-20 MHz)



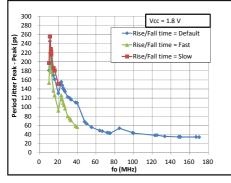
Period Jitter RMS

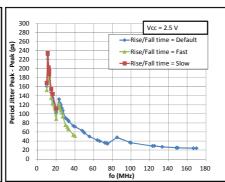


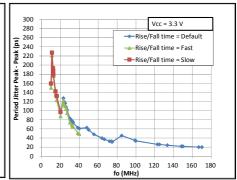




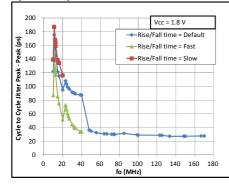
Period Jitter Peak-Peak

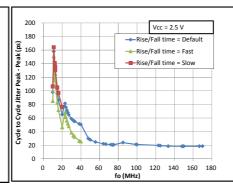


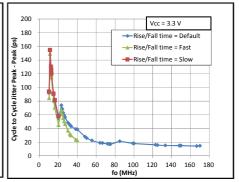




Cycle-to-Cycle Jitter Peak-Peak





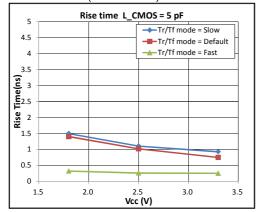


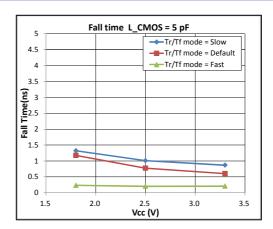
■ Notes:

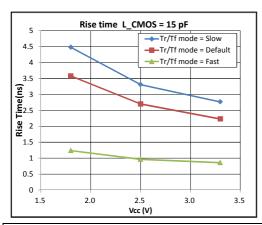


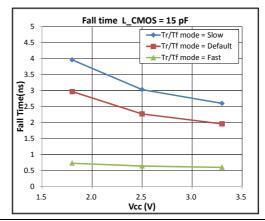
Specification Graph (Typical supplemental specification. Unless otherwise specified T_use = 25 °C, L_CMOS = 15pF)

Rise/Fall Time (fo = 20 MHz)





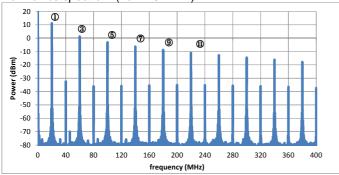




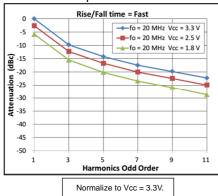
■ Notes:

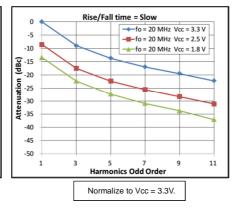
frequency	slow	default	fast
0.67 M - 20 M	See Slow	See Default	See Fast
20 M – 40 M	-	See Default	See Fast
40 M – 170 M	-	See Fast	See Fast

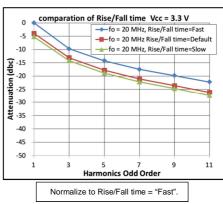




Harmonics comparison







■Notes:



ESD Rating

Test items	Breakdown voltage
Human Body Model (HBM)	2000V
Machine Model (MM)	250V
Charged Device Model (CDM)	750V

Device Marking (Standard specification)

Model	Factory Programmed Part Marking	Field Programmable Part Marking (Blank Samples)
SG-8101CG	Frequency Product code 170. A1 OA23DK 1pin mark Lot No.	A1 OA23DK Lot No.
SG-8101CE	Frequency Product code 170.0A1 o A23DK 1pin mark Lot No.	A1 o A23DK Lot No.
SG-8101CB	Frequency 170.0A1 O A23DK Lot No.	A1 A23DK Lot No.
SG-8101CA	Frequency 170.00A1 o A23DK 1pin mark Lot No.	A1 O A23DK Lot No.

Simulation Model

• IBIS Model is available upon request. Please contact us. Information Required: Oscillator operating condition (i.e. Power Supply, Rise/Fall Time, Temperature)

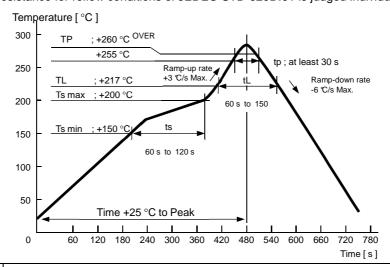


Device Material & Environmental Information

Model	Package	# of	Reference	Terminal	Terminal	Complies	Pb	MSL	Peak
	Dimensions	Pins	Weight	Material	Plating	With EU	Free	Rating	Temp.
			(Typ.)			RoHS			(Max)
SG-8101CG	2.5 x 2.0 x 0.7 mm	4	13 mg	W	Au	Yes	Yes	1	260°C
SG-8101CE	3.2 x 2.5 x 1.0 mm	4	25 mg	W	Au	Yes	Yes	1	260°C
SG-8101CB	5.0 x 3.2 x 1.1 mm	4	51 mg	W	Au	Yes	Yes	1	260°C
SG-8101CA	7.0 x 5.0 x 1.3 mm	4	143 mg	W	Au	Yes	Yes	1	260°C

SMD products Reflow profile(example)

The availability of the heat resistance for reflow conditions of JEDEC-STD-020D.01 is judged individually. Please inquire.





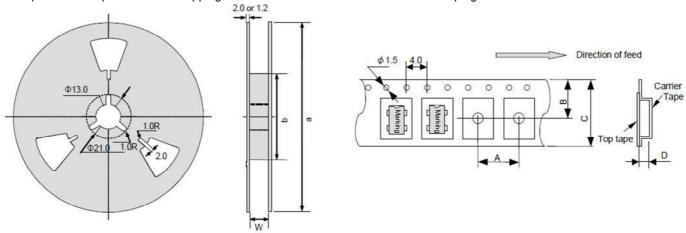
Pb free.



- Complies with EU RoHS directive.
 - About the products without the Pb-free mark.
 Contains Pb in products exempted by EU RoHS directive.
 (Contains Pb in sealing glass, high melting temperature type solder or other.)

Standard Packing Specification

SMD products are packed in the shipping carton as below table in accordance with taping standards EIA-481 and IEC-60286



Standard Packing Quantity & Dimension(Unit mm)

	Quantity	Reel Dimension			Car	Direction of			
Model	(pcs/Reel)	а	b	W	А	В	С	D	Feed (L= Left Direction)
SG-8101CG	3000	Ф180	Ф60	9	4	5.25	8	1.15	L
SG-8101CE	2000	Ф180	Ф60	9	4	5.25	8	1.4	L
SG-8101CB	1000	Ф180	Ф60	13	8	7.25	12	1.4	L
SG-8101CA	1000	Ф254	Ф100	17.5	8	9.25	16	2.3	L

PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

At Seiko Epson, all environmental initiatives operate under the Plan-Do-Check-Action (PDCA) cycle designed to achieve continuous improvements. The environmental management system (EMS) operates under the ISO 14001 environmental management standard.

All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

WORKING FOR HIGH QUALITY

In order provide high quality and reliable products and services than meet customer needs.

Seiko Epson made early efforts towards obtaining ISO9000 series certification and has acquired ISO9001 for all business establishments in Japan and abroad. We have also acquired ISO/TS 16949 certification that is requested strongly by major automotive manufacturers as standard.

ISO/TS16949 is the international standard that added the sector-specific supplemental requirements for automotive industry based on ISO9001.

Explanation of the mark that are using it for the catalog



►Pb free.



- ► Complies with EU RoHS directive.
 - *About the products without the Pb-free mark.

 Contains Pb in products exempted by EU RoHS directive.

 (Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.



▶ Designed for automotive applications related to driving safety (Engine Control Unit, Air Bag, ESC etc.).

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Socket for 7050 case S5U1C17W36T2100 MC-306 32.7680K-E ROHS MA-505 24.0000M-C0:ROHS S5U13513P00C100

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644.53125MLGPA SG-636PCE 25.0000MC3:ROHS MA-506 4.0000M-C3 ROHS EG-2121CA2000000M-LGPAL3 S5U13U00P00C100

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SG-210STF 7.3728ML3 FC-12M 32.7680KA-AC0 M150 S5U1C17W15T2100 XG-2121CA 156.2500M-PGSNB SG-210STF 32.7680ML

SG-636PTF 20.0000MC3: ROHS SG-210STF 27.0000ML0 SG-8002JC MP BLANK:ROHS SG5032CCN 14.745600M-HJGA3 SG-615P

2.0000MC: ROHS Q13FC13F00001 FC-13F 32.768KHZ 12.5PF MA-306 18.4320M-C0:ROHS EG-2121CA 156.2500M-LHPAB